

AMENDMENTS TO THE SPECIFICATION:

Please replace the title with the following:

--"IMAGE DISPLAY APPARATUS WITH FIRST AND SECOND SUBSTRATES
IN A HERMETIC CONTAINER SEALED BY A CONDUCTIVE BONDING MEMBER
THEREBETWEEN"--

Please replace the paragraph starting at line 3 of page 26 and ending at line 1 of page 28 with the following:

--As shown in FIG. 2, the electron source area 201 is so configured as to be laid out in a position that faces an image forming area 102. An external frame 202 is disposed between the face plate 101 and the rear plate 103 and is formed by working in a frame-like shape the same glass material as the face plate 101 and the rear plate 103 are composed of. The external frame is fixedly bonded to the rear plate 103 by use of a frit 203, and this frit (LS3081) utilized in this example 1 is made by Nippon Electric Glass Co., Ltd. A bonding member ~~A204~~ 204 is composed of In and coated over an upper surface of the external frame 202. In this example 1, In is adopted as a connecting material having both of a bonding function and a hermetic connecting function. An insulation area 205 ensures a creepage distance in order to secure a withstand voltage, and a base material 200 is a material (such as Ag, Cu, In, Au, Ni, Ti, etc.) capable enhancing bondability of the bonding member. A bonding member ~~B206~~ 206 is formed by coating the in material over the surface, on the side of the image forming area, of the face plate 103 in a position opposite to the bonding member ~~A204~~ 204. A coating width of each of the face plate 101 and the rear plate 103 is set narrower than a width of the external frame 202 excluding the

corner portions inconsideration of sagging on the occasion of bonding the face plate 101 and the rear plate 103 together by heating them up to a melting point of the bonding member (a manufacturing method thereof will be explained later on). As shown in FIGS. 4A and 4B, at the corner, when bonding the face plate 101 and the rear plate 103 to each other by heating them, the materials of the bonding member ~~A204~~ 204 and of the bonding member ~~B206~~ 206 are bonded together and overhang as sagging in a form that extends along the shape of the external frame 202. The pointed overhang becomes an origin from which an extra material of the molten bonding members ~~A204~~ 204 and ~~B206~~ 206 bonded together flows first. Further, a thickness of each of the bonding member 204 and the bonding member B206 is adjusted not to protrude from the external frame 202 excluding the corners when bonding the face plate 101 and the rear plate 103 to each other. The bonding members protruding from the corners reach the rear plate via the outer side surfaces of the external frame and come into contact with potential specifying electrodes 106 formed at the four corners of the rear plate 103. A proper electric potential (e.g., a ground level) is applied to this potential specifying electrode, whereby an electric potential of the bonding member ~~B206~~ 206 of the face plate 101 can be specified on the side of the rear plate 103.--

Please replace the paragraph starting at line 2 of page 28 and ending at line 15 of page 28 with the following:

--Accordingly, in this mode, the materials of the bonding member ~~A204~~ 204 and of the bonding member ~~B206~~ 206 are bonded into one united body, the portion positioned between the external frame and the first substrate at that time becomes the first conductive member, and

the portion protruding from the opposite surface and formed on the outer side surface along the external frame 202 corresponds to the second conductive member. According to this example 1, the sagging portion of the same connecting material as that of the first conductive member becomes the second conductive member, and hence it is preferable that the second conductive member be composed of the same material as that of the first conductive member.--